



QUALCOMM Incorporated

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May 13, 2010

Via Email and Federal Express

President

ATSC

1750 K Street NW

Washington, D.C. 20006

(Facsimile): 202-872-9161

Re: QUALCOMM Incorporated's IPR Declaration of May 13, 2010 for ATSC Specification, ATSC NRT entitled, "Non-Real-Time Content Delivery"

Dear Sir,

Enclosed please find Qualcomm Incorporated's IPR Disclosure Statement and Licensing Declaration for ATSC Specification, ATSC NRT entitled, "Non-Real-Time Content Delivery".

Please confirm receipt of this declaration at your earliest convenience via email to syoung@qualcomm.com. If you have any questions or concerns, please contact me directly at 858-658-4851. Thank you for your time and assistance with this matter.

Sincerely,

A handwritten signature in blue ink, appearing to read "Stephanie F. Young", with a long, sweeping flourish extending to the right.

Stephanie F. Young
Sr. Manager
Intellectual Property Administration
QUALCOMM Incorporated

cc: Thomas R. Rouse
VP, QTL Patent Counsel
Qualcomm Incorporated

Disclosure of Patents _____

In accordance with Sections 3 and 4 of the ATSC Patent Policy, please identify each patent or patent application forming the subject matter of any Potential Claim of which any Representative of the Discloser who is active in an ATSC technology group or specialist group has actual personal knowledge. The Discloser, in good faith, believes that the Potential Claim may be relevant to the implementation of the Specification Document identified by this Disclosure Statement.

No.	Patent/Application No.	and Country	Patent/Application Holder	Status [granted/pending]
1	6,728,300	United States of America	QUALCOMM Incorporated	Granted
	PI0108218-3	Brazil		Application
	6,977,957	United States of America		Granted
	7,519,106	United States of America		Granted
	12/420,900	United States of America		Application
	ZL01807716.1	China		Granted
	1254579	Germany (Federal Republic of)		Granted
	EP1254579	European Patent		Granted
	EP1885152	European Patent		Granted
	EP1885152	Belgium		Granted
	EP1885152	Germany (Federal Republic of)		Granted
	EP1885152	Spain		Granted
	EP1885152	Finland		Granted
	EP1885152	France		Granted
	EP1885152	United Kingdom		Granted
	HKI 115262	Hong Kong		Granted
	EP1885152	Italy		Granted
	EP1885152	Netherlands		Granted
	EP1885152	Sweden		Granted
	08166976.4	European Patent		Application
	09108006.6	Hong Kong		Application
	1254579	France		Granted
	1254579	United Kingdom		Granted
	1056811	Hong Kong		Granted
	2001-557822	Japan		Application
	797660	Korea Republic of (KR)		Granted
	NI-189336	Taiwan		Granted
2	6,980,823	United States of America	QUALCOMM Incorporated	Granted
	03803108.6	China		Allowed

	05107840.2	Hong Kong		Application
	1662/CHENP/2004	India		Application
	2003-565192	Japan		Application
	2009-066166	Japan		Application
	940467	Korea Republic of (KR)		Granted
3	7,203,319	United States of America	QUALCOMM Incorporated	Granted
	PI0210946-8	Brazil		Application
	2453109	Canada		Application
	ZL02817148.9	China		Granted
	02746834.7	European Patent		Application
	HK1070773	Hong Kong		Granted
	237693	India		Granted
	2003-513243	Japan		Application
	939463	Korea Republic of (KR)		Granted
	247001	Mexico		Granted
4	6,985,589	United States of America	QUALCOMM Incorporated	Granted
	AR035021B1	Argentina		Granted
	AR058202B2	Argentina		Granted
	2005242186	Australia		Application
	PI0016107-1	Brazil		Application
	11/030,353	United States of America		Application
	CL43.821	Chile		Granted
	ZL00818700.2	China		Granted
	00980844.5	European Patent		Application
	1055524	Hong Kong		Granted
	149658	Israel		Granted
	212920	India		Granted
	2001-541246	Japan		Application
	2008-190889	Japan		Application
	751648	Korea Republic of (KR)		Granted
	PI20005595	Malaysia		Application
	248258	Mexico		Granted
	PA/a/2006/008192	Mexico		Application
	519095	New Zealand		Granted
	NI-169543	Taiwan		Granted
	2257015	Russian Federation		Granted

	89026	Singapore		Granted
	062147	Thailand		Application
	2002/4074	South Africa		Granted
5	7,720,515	United States of America	QUALCOMM Incorporated	Granted
	ZL02810532.X	China		Granted
	HK1064239	Hong Kong		Granted
	229927	India		Granted
	246218	Mexico		Granted
6	2002227359	Australia	QUALCOMM Incorporated	Granted
	2006230711	Australia		Application
	2009200172	Australia		Application
	PI0116157-1	Brazil		Application
	2431492	Canada		Application
	ZL01822583.7	China		Granted
	200710087664.6	China		Application
	HK1067477	Hong Kong		Granted
	07112326.3	Hong Kong		Application
	156385	Israel		Application
	196245	Israel		Application
	196244	Israel		Application
	196246	Israel		Application
	196247	Israel		Application
	214324	India		Granted
	3211/CHENP/2007	India		Application
	10-0944843	Korea Republic of (KR)		Granted
	10-2009-7016066	Korea Republic of (KR)		Application
	241443	Mexico		Granted
7	7,352,868	United States of America	QUALCOMM Incorporated	Granted
	2002342014	Australia		Granted
	PI0213214-1	Brazil		Application
	12/039,661	United States of America		Application
	2463542	Canada		Application
	ZL02823862.1	China		Granted
	200910128921.5	China		Application
	10100858.9	Hong Kong		Application
	02776178.2	European Patent		Application

	HK1076553	Hong Kong		Granted
	ID0022422	Indonesia		Granted
	161312	Israel		Allowed
	739/CHENP/2004	India		Application
	2003-535411	Japan		Application
	2004-7005321	Korea Republic of (KR)		Allowed
	257252	Mexico		Granted
	2333608	Russian Federation		Granted
	103676	Singapore		Granted
	I256223	Taiwan		Granted
8	6,876,636	United States of America	QUALCOMM Incorporated	Granted
	PI0312518-1	Brazil		Application
	11/097,594	United States of America		Application
	ZL03821188.2	China		Granted
	200710180375.0	China		Application
	03763448.2	European Patent		Application
	HK1083287	Hong Kong		Granted
	08109487.3	Hong Kong		Application
	2004-520111	Japan		Application
	2009-180888	Japan		Application
	2005-7000237	Korea Republic of (KR)		Application
	092118782	Taiwan		Application
9	10/282,797	United States of America	QUALCOMM Incorporated	Allowed
10	10/368,733	United States of America	QUALCOMM Incorporated	Allowed
	P040100506	Argentina		Application
	P100101491	Argentina		Application
	2004213979	Australia		Granted
	PI0407577-3	Brazil		Application
	12/170,560	United States of America		Application
	12/622,202	United States of America		Application
	2516529	Canada		Application
	200480006245.X	China		Application
	20091023726.3	China		Application
	04711906.0	European Patent		Application
	06109305.5	Hong Kong		Application
	224021	India		Granted

	4430662	Japan		Granted
	260414	Mexico		Granted
	MY-140101-A	Malaysia		Granted
	093103846	Taiwan		Application
	098142815	Taiwan		Application
11	10/748,603	United States of America	QUALCOMM Incorporated	Application
	PI0406882-3	Brazil		Application
	200480004398.0	China		Application
	04704474.8	European Patent		Application
	06105999.4	Hong Kong		Application
	169737	Israel		Application
	227144	India		Granted
	2006-501115	Japan		Application
	2005-7013505	Korea Republic of (KR)		Application
	260941	Mexico		Granted
12	10/615,882	United States of America	QUALCOMM Incorporated	Application
	P040102442	Argentina		Application
	2004300912	Australia		Application
	PI0412398-0	Brazil		Application
	2531502	Canada		Application
	200480019592.6	China		Allowed
	04777742.0	European Patent		Application
	07112483.2	Hong Kong		Application
	172931	Israel		Application
	237135	India		Granted
	2006-518892	Japan		Application
	2006-7000456	Korea Republic of (KR)		Application
	266583	Mexico		Granted
	1-2006-500081	Philippines		Application
	2356170	Russian Federation		Granted
	118797	Singapore		Granted
	092128	Thailand		Application
	093120523	Taiwan		Application
	1-2006-00179	Vietnam		Application
13	7,221,680	United States of America	QUALCOMM Incorporated	Granted
	P040103138	Argentina		Application

	2004302856	Australia		Application
	PI0414065-6	Brazil		Application
	11/751,631	United States of America		Application
	2537534	Canada		Application
	2230-2004	Chile		Application
	200480032549.3	China		Application
	04783049.2	European Patent		Application
	07103045.2	Hong Kong		Application
	174046	Israel		Application
	236666	India		Granted
	2006-525457	Japan		Application
	2006-7004397	Korea Republic of (KR)		Application
	267326	Mexico		Granted
	1-2006-500437	Philippines		Granted
	2368083	Russian Federation		Granted
	2009123799	Russian Federation		Application
	119999	Singapore		Granted
	093447	Thailand		Application
	093126567	Taiwan		Application
	7359	Vietnam		Granted
14	10/968,702	United States of America	QUALCOMM Incorporated	Application
	P040103882	Argentina		Application
	2004307138	Australia		Granted
	PI0415856-3	Brazil		Application
	2543414	Canada		Application
	CL45.014	Chile		Granted
	ZL200480038813.4	China		Application
	04796065.3	European Patent		Application
	07112853.4	Hong Kong		Application
	175102	Israel		Application
	2224/DELNP/2006	India		Application
	4481995	Japan		Granted
	2009-272313	Japan		Application
	10-2006-7010082	Korea Republic of (KR)		Application
	10-0877536	Korea Republic of (KR)		Granted
	265281	Mexico		Granted

	1-2006-500815	Philippines		Application
	2345485	Russian Federation		Granted
	121625	Singapore		Granted
	094799	Thailand		Application
	093132299	Taiwan		Application
	1-2006-00817	Vietnam		Application
15	7,366,462	United States of America	QUALCOMM Incorporated	Granted
	P040103883	Argentina		Application
	2004286625	Australia		Application
	2009200088	Australia		Application
	PI0415640-4	Brazil		Application
	11/752,291	United States of America		Allowed
	2543141	Canada		Application
	2716-2004	Chile		Application
	200480038715.0	China		Application
	04795971.3	European Patent		Application
	10155803.9	European Patent		Application
	10155805.4	European Patent		Application
	10155807.0	European Patent		Application
	10155810.4	European Patent		Application
	08102443.1	Hong Kong		Application
	175049	Israel		Application
	2223/DELNP/2006	India		Application
	2006-536787	Japan		Application
	2009-283611	Japan		Application
	2009-283612	Japan		Application
	2009-283613	Japan		Application
	10-2006-7009796	Korea Republic of (KR)		Application
	10-2009-7020012	Korea Republic of (KR)		Application
	264550	Mexico		Granted
	1-2006-500814	Philippines		Granted
	2006117791	Russian Federation		Application
	121607	Singapore		Granted
	094800	Thailand		Application
	093132165	Taiwan		Application
	1-2006-00818	Vietnam		Application

16	7,493,133	United States of America	QUALCOMM Incorporated	Granted
	200580010206.1	China		Application
	05712850.6	European Patent		Application
	07106458.5	Hong Kong		Application
	4594/DELNP/2006	India		Application
	2006-552261	Japan		Allowed
	801386	Korea Republic of (KR)		Granted
	094104037	Taiwan		Application
17	7,702,351	United States of America	QUALCOMM Incorporated	Granted
	200680012834.8	China		Application
	7,701,911	United States of America		Granted
	06735446.4	European Patent		Application
	08108664.0	Hong Kong		Application
	1371/MUMNP/2007	India		Application
	2007-556354	Japan		Application
	943869	Korea Republic of (KR)		Granted
	095105534	Taiwan		Application
18	200780018722.8	China	QUALCOMM Incorporated	Application
	6012/CHENP/2008	India		Application
	2009-512306	Japan		Application
	2008-7031388	Korea Republic of (KR)		Application
	096118574	Taiwan		Application
19	11/692,099	United States of America	QUALCOMM Incorporated	Application
	200780007735.5	China		Application
	07760140.9	European Patent		Application
	6585/DELNP/2008	India		Application
	2009-504468	Japan		Application
	2008-7026997	Korea Republic of (KR)		Application
	096112214	Taiwan		Application
20	7,555,012	United States of America	QUALCOMM Incorporated	Granted
	2565672	Canada		Application
	200580019264.0	China		Application
	12/472,253	United States of America		Application
	05753001.6	European Patent		Application
	07109941.4	Hong Kong		Application
	6847/DELNP/2006	India		Application

	2007-511538 907845	Japan Korea Republic of (KR)		Application Granted
21	11/116,891 2565564 1026-2005 200580022395.4 05745231.0 07122090.7 6635/DELNP/2006 2007-511495 900167 PI20051951 100082 094114327	United States of America Canada Chile China European Patent Hong Kong India Japan Korea Republic of (KR) Malaysia Thailand Taiwan	QUALCOMM Incorporated	Application Application Application Application Application Application Application Application Granted Application Application Application
22	11/120,584 2565792 200580022307.0 05743097.7 07112350.2 6852/DELNP/2006 2007-51135 808032 PI20051965 100083 094114413	United States of America Canada China European Patent Hong Kong India Japan Korea Republic of (KR) Malaysia Thailand Taiwan	QUALCOMM Incorporated	Application Application Application Application Application Application Allowed Granted Application Application Application
23	11/612,453 200780024353.3 07798868.1 6774/CHENP/2008 2009-518467 2009-7001913 096123912	United States of America China European Patent India Japan Korea Republic of (KR) Taiwan	QUALCOMM Incorporated	Application Application Application Application Application Application Application
24	11/111,050 2005239606 PI0510040-2 2562753	United States of America Australia Brazil Canada	QUALCOMM Incorporated	Application Granted Application Application

	200580020403.1	China		Application
	05736286.5	European Patent		Application
	07111963.3	Hong Kong		Application
	178658	Israel		Application
	6046/DELNP/2006	India		Application
	2007-509719	Japan		Application
	10-2006-7024252	Korea Republic of (KR)		Application
	272480	Mexico		Granted
	1-2006-502050	Philippines		Application
	2354068	Russian Federation		Granted
	200607265-6	Singapore		Application
	094112747	Taiwan		Application
	1-2006-01916	Vietnam		Application
25	11/139,302	United States of America	QUALCOMM Incorporated	Application
	PI0610990-0	Brazil		Application
	2606561	Canada		Application
	200680023341.4	China		Application
	06759158.6	European Patent		Application
	2001/MUMNP/2007	India		Application
	2008-510260	Japan		Application
	2007-7028342	Korea Republic of (KR)		Allowed
	PI20062087	Malaysia		Application
	2007145053	Russian Federation		Application
	200717452-7	Singapore		Application
	095116087	Taiwan		Application
26	11/186,153	United States of America	QUALCOMM Incorporated	Application
	2005267858	Australia		Granted
	EP1794985	Belgium		Granted
	EP1794985	Bulgaria		Granted
	PI0513884-1	Brazil		Application
	2575331	Canada		Application
	200580033421.3	China		Application
	EP1794985	Czech Republic		Granted
	EP1794985	Germany (Federal Republic of)		Granted
	EP1794985	European Patent		Granted
	EP1794985	Spain		Granted

	EP1794985	Finland		Granted
	EP1794985	France		Granted
	EP1794985	United Kingdom		Granted
	08101672.5	Hong Kong		Application
	EP1794985	Hungary		Granted
	EP1794985	Ireland (Republic of)		Granted
	181004	Israel		Application
	789/DELNP/2007	India		Application
	EP1794985	Italy		Granted
	2007-523851	Japan		Application
	930853	Korea Republic of (KR)		Granted
	MX/a/2007/001164	Mexico		Application
	EP1794985	Netherlands		Granted
	1-2007-500267	Philippines		Application
	EP1794985	Poland		Granted
	EP1794985	Romania		Granted
	2369979	Russian Federation		Granted
	EP1794985	Sweden		Granted
	129579	Singapore		Granted
	094125878	Taiwan		Application
	1-2007-00441	Vietnam		Application
27	11/373,613	United States of America	QUALCOMM Incorporated	Application
28	7,603,109	United States of America	QUALCOMM Incorporated	Granted
	2006223207	Australia		Allowed
	EP1864526	Belgium		Granted
	EP1864526	Bulgaria		Granted
	PI0607626-2	Brazil		Application
	2600483	Canada		Application
	200680014639.9	China		Application
	EP1864526	Czech Republic		Granted
	12/553,660	United States of America		Application
	EP1864526	Germany (Federal Republic of)		Granted
	EP1864526	European Patent		Granted
	09177265.7	European Patent		Application
	EP1864526	Spain		Granted
	EP1864526	Finland		Granted

	EP1864526	France		Granted
	EP1864526	United Kingdom		Granted
	08108723.9	Hong Kong		Application
	EP1864526	Hungary		Granted
	W-00200703436	Indonesia		Application
	EP1864526	Ireland (Republic of)		Granted
	185821	Israel		Application
	1550/MUMNP/2007	India		Application
	EP1864526	Italy		Granted
	2008-501013	Japan		Application
	2007-7022550	Korea Republic of (KR)		Application
	2010-7009559	Korea Republic of (KR)		Application
	271852	Mexico		Granted
	EP1864526	Netherlands		Granted
	20075138	Norway		Application
	561389	New Zealand		Granted
	1-2007-501965	Philippines		Application
	EP1864526	Poland		Granted
	2007137515	Russian Federation		Allowed
	EP1864526	Sweden		Granted
	135478	Singapore		Granted
	200711174	Ukraine		Allowed
	1-2007-02071	Vietnam		Allowed
29	11/270,199	United States of America	QUALCOMM Incorporated	Application
	PI060103933	Argentina		Application
	PI0615569-3	Brazil		Application
	2621680	Canada		Application
	200680040410.2	China		Application
	09110326.5	Hong Kong		Application
	06803088.1	European Patent		Application
	489/MUMNP/2008	India		Application
	2008-530188	Japan		Application
	10-2008-7008375	Korea Republic of (KR)		Application
	2008113395	Russian Federation		Allowed
	200801910-1	Singapore		Allowed
	0601004321	Thailand		Application

	095133322	Taiwan		Application
30	11/373,021	United States of America	QUALCOMM Incorporated	Allowed
	200680013490.2	China		Application
	06737645.9	European Patent		Application
	08108240.3	Hong Kong		Application
	1527/MUMNP/2007	India		Application
	2008-500937	Japan		Application
	930857	Korea Republic of (KR)		Granted
	PI20061062	Malaysia		Application
	095108421	Taiwan		Application
31	11/369,465	United States of America	QUALCOMM Incorporated	Application
	2006223191	Australia		Application
	PI0609288-8	Brazil		Application
	2600680	Canada		Application
	200680013392.9	China		Application
	06738049.3	European Patent		Application
	08108053.9	Hong Kong		Application
	W-00200703437	Indonesia		Application
	185883	Israel		Application
	1553/MUMNP/2007	India		Application
	2008-501030	Japan		Application
	930856	Korea Republic of (KR)		Granted
	MX/a/2007/011092	Mexico		Allowed
	20075076	Norway		Application
	561315	New Zealand		Application
	1-2007-501964	Philippines		Application
	200706746-5	Singapore		Allowed
	88685	Ukraine		Granted
	1-2007-02048	Vietnam		Application
32	11/369,464	United States of America	QUALCOMM Incorporated	Application
	2006223128	Australia		Application
	EP1856850	Belgium		Granted
	EP1856850	Bulgaria		Granted
	PI0609238-1	Brazil		Application
	2600785	Canada		Application
	200680015190.8	China		Application

	EP1856850	Czech Republic		Granted
	EP1856850	Germany (Federal Republic of)		Granted
	EP1856850	European Patent		Granted
	09173556.3	European Patent		Application
	EP1856850	Spain		Granted
	EP1856850	Finland		Granted
	EP1856850	France		Granted
	EP1856850	United Kingdom		Granted
	08108344.8	Hong Kong		Application
	EP1856850	Hungary		Granted
	W-00200702940	Indonesia		Application
	EP1856850	Ireland (Republic of)		Granted
	185792	Israel		Application
	EP1856850	Italy		Granted
	2008-501046	Japan		Application
	910950	Korea Republic of (KR)		Granted
	MX/a/2007/011085	Mexico		Granted
	EP1856850	Netherlands		Granted
	20075079	Norway		Application
	561314	New Zealand		Application
	1-2007-501963	Philippines		Application
	EP1856850	Poland		Granted
	EP1856850	Romania		Granted
	2376714	Russian Federation		Granted
	EP1856850	Sweden		Granted
	200706623-6	Singapore		Application
	095108156	Taiwan		Application
	200711181	Ukraine		Allowed
	1-2007-02059	Vietnam		Application
33	7,653,085	United States of America	QUALCOMM Incorporated	Granted
	200680019334.7	China		Application
	EP1867114	Germany (Federal Republic of)		Granted
	EP1867114	European Patent		Granted
	EP1867114	Spain		Granted
	EP1867114	Finland		Granted
	EP1867114	France		Granted

	EP1867114	United Kingdom		Granted
	08109863.7	Hong Kong		Application
	1820/MUMNP/2007	India		Application
	EP1867114	Italy		Granted
	2008-505670	Japan		Application
	10-2007-7025993	Korea Republic of (KR)		Application
	EP1867114	Netherlands		Granted
	EP1867114	Sweden		Granted
	095112653	Taiwan		Allowed
34	11/400,619	United States of America	QUALCOMM Incorporated	Application
	200680019627.5	China		Application
	06749632.3	European Patent		Application
	08110386.3	Hong Kong		Application
	2008-505621	Japan		Application
	10-2007-7025877	Korea Republic of (KR)		Allowed
	PI20061606	Malaysia		Application
	095112587	Taiwan		Application
35	11/392,291	United States of America	QUALCOMM Incorporated	Application
	PI0609753-7	Brazil		Application
	2604001	Canada		Application
	200680019636.4	China		Application
	06740616.5	European Patent		Application
	08110164.1	Hong Kong		Application
	1708/MUMNP/2007	India		Application
	2008-505518	Japan		Application
	10-2007-7025768	Korea Republic of (KR)		Application
	2378799	Russian Federation		Granted
	200716702-6	Singapore		Allowed
	200907066-5	Singapore		Application
	095112570	Taiwan		Application
36	11/612,450	United States of America	QUALCOMM Incorporated	Application
	PI0706744-5	Brazil		Application
	2637048	Canada		Application
	200780003601.6	China		Application
	09106750.8	Hong Kong		Application
	07710341.4	European Patent		Application

	3575/CHENP/2008	India		Application
	2008-552597	Japan		Application
	2008-7021061	Korea Republic of (KR)		Application
	2008134882	Russian Federation		Application
	200804972-8	Singapore		Application
	0701000400	Thailand		Application
	096103236	Taiwan		Application
37	11/527,306	United States of America	QUALCOMM Incorporated	Application
	AR061395B1	Argentina		Granted
	2586-2006	Chile		Application
	200680043443.2	China		Application
	06815726.2	European Patent		Application
	09104721.9	Hong Kong		Application
	704/MUMNP/2008	India		Application
	2008-533617	Japan		Application
	10-2008-7009996	Korea Republic of (KR)		Allowed
	0601004755	Thailand		Application
	095135836	Taiwan		Application
38	7,706,288	United States of America	QUALCOMM Incorporated	Granted
	12/722,308	United States of America		Application
	200680044041.4	China		Application
	09110096.3	Hong Kong		Application
	06815753.6	European Patent		Application
	2552/DELNP/2008	India		Application
	2008-533638	Japan		Application
	10-2008-7010172	Korea Republic of (KR)		Application
	095135860	Taiwan		Application
39	11/270,372	United States of America	QUALCOMM Incorporated	Application
	PI0615809-9	Brazil		Application
	2622144	Canada		Application
	200680041815.8	China		Application
	06803405.7	European Patent		Application
	09104336.6	Hong Kong		Application
	558/MUMNP/2008	India		Application
	2008-531244	Japan		Application
	2008-7008793	Korea Republic of (KR)		Application

	2008114383	Russian Federation		Allowed
	140838	Singapore		Granted
	095133703	Taiwan		Application
40	11/270,166	United States of America	QUALCOMM Incorporated	Application
	PI0615806-4	Brazil		Application
	2622140	Canada		Application
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	06803404.0	European Patent		Application
	554/MUMNP/2008	India		Application
	2008-531243	Japan		Application
	10-2008-7008204	Korea Republic of (KR)		Application
	2008114384	Russian Federation		Application
	200801963-0	Singapore		Allowed
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41	11/270,370	United States of America	QUALCOMM Incorporated	Application
	P060103953	Argentina		Application
	PI0615808-0	Brazil		Application
	2622309	Canada		Application
	200680040616.5	China		Application
	09104043.0	Hong Kong		Application
	06814606.7	European Patent		Application
	561/MUMNP/2008	India		Application
	2008-531287	Japan		Application
	21672	Korea Republic of (KR)		Granted
	2008114342	Russian Federation		Allowed
	200801962-2	Singapore		Application
	0601004369	Thailand		Application
	095132748	Taiwan		Application
42	11/561,310	United States of America	QUALCOMM Incorporated	Application
	200680051215.X	China		Application
	06851186.4	European Patent		Application
	09104328.6	Hong Kong		Application
	4852/DELNP/2008	India		Application
	2008-542526	Japan		Application
	2008-7015268	Korea Republic of (KR)		Application

	095143426	Taiwan		Application
43	11/270,210	United States of America	QUALCOMM Incorporated	Application
	PI0618340-9	Brazil		Application
	2628464	Canada		Application
	200680050525.X	China		Application
	06839780.1	European Patent		Application
	09100736.0	Hong Kong		Application
	936/MUMNP/2008	India		Application
	2008-540333	Japan		Application
	10-2008-7013604	Korea Republic of (KR)		Application
	2008122932	Russian Federation		Application
	200803504-0	Singapore		Application
44	11/270,165	United States of America	QUALCOMM Incorporated	Application
	PI0618341-7	Brazil		Application
	2628616	Canada		Application
	200680050646.4	China		Application
	06839779.3	European Patent		Application
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	942/MUMNP/2008	India		Application
	2008-540332	Japan		Application
	2008-7013860	Korea Republic of (KR)		Application
	2008122983	Russian Federation		Allowed
	200803505-7	Singapore		Application
45	11/270,167	United States of America	QUALCOMM Incorporated	Allowed
	PI0618342-5	Brazil		Application
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	200680050524.5	China		Application
	09106522.5	Hong Kong		Application
	06839781.9	European Patent		Application
	937/MUMNP/2008	India		Application
	2008-540334	Japan		Application
	10-2008-7013868	Korea Republic of (KR)		Application
	2008122963	Russian Federation		Application
	200803502-4	Singapore		Application
46	11/564,753	United States of America	QUALCOMM Incorporated	Allowed
	3368-2006	Chile		Application

	200680045118.X	China		Application
	06850225.1	European Patent		Application
	09101313.9	Hong Kong		Application
	4510/DELNP/2008	India		Application
	2008-543596	Japan		Application
	10-2008-7015974	Korea Republic of (KR)		Application
	095145052	Taiwan		Application
47	11/612,451	United States of America	QUALCOMM Incorporated	Application
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	2631577	Canada		Application
	200780001955.7	China		Application
	09106596.6	Hong Kong		Application
	07777504.7	European Patent		Application
	5521/DELNP/2008	India		Application
	2008-549645	Japan		Application
	10-2008-7018939	Korea Republic of (KR)		Application
	2008131952	Russian Federation		Application
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	096100268	Taiwan		Application
48	11/566,145	United States of America	QUALCOMM Incorporated	Application
	200780018644.1	China		Application
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49	11/677,031	United States of America	QUALCOMM Incorporated	Application
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	2008-7023000	Korea Republic of (KR)		Application
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50	11/558,858	United States of America	QUALCOMM Incorporated	Application
	PI0713437-1	Brazil		Application
	2654285	Canada		Application
	200780024289.9	China		Application
	07798719.6	European Patent		Application
	2586/MUMNP/2008	India		Application
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	2009102978	Russian Federation		Application
	200809072-2	Singapore		Application
	096123819	Taiwan		Application
51	12/474,057	United States of America	QUALCOMM Incorporated	Application
	098118091	Taiwan		Application
	PCT/US2009/045619	Patent Cooperation Treaty		Application
52	12/133,975	United States of America	QUALCOMM Incorporated	Application
	PCT/US2009/031278	Patent Cooperation Treaty		Application
53	11/738,241	United States of America	QUALCOMM Incorporated	Application
	200780011025.X	China		Application
	07761042.6	European Patent		Application
	5143/CHENP/2008	India		Application
	2009-506802	Japan		Application
	2008-7028469	Korea Republic of (KR)		Application
54	11/683,343	United States of America	QUALCOMM Incorporated	Application
	2008222692	Australia		Application
	PI0808641-9	Brazil		Application
	2677924	Canada		Application
	200880007399.9	China		Application
	08731741.8	European Patent		Application
	W-00200902479	Indonesia		Application
	200411	Israel		Application
	4936/CHENP/2009	India		Application
	2009-552919	Japan		Application
	10-2009-7020967	Korea Republic of (KR)		Application
	MX/a/2009/009527	Mexico		Application
	PI 20093500	Malaysia		Application

	578995	New Zealand		Application
	1-2009-501551	Philippines		Application
	2009137022	Russian Federation		Application
	200905405-7	Singapore		Application
	097108243	Taiwan		Application
	200910154	Ukraine		Application
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55	11/612,986	United States of America	QUALCOMM Incorporated	Allowed
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	6342/CHENP/2008	India		Application
	2009-514543	Japan		Application
	10-2009-7000401	Korea Republic of (KR)		Application
	096120911	Taiwan		Application
56	11/691,146	United States of America	QUALCOMM Incorporated	Application
	PI0718617-7	Brazil		Application
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	07844912.1	European Patent		Application
	2444/CHENP/2009	India		Application
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	10-2009-7012382	Korea Republic of (KR)		Application
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	096142904	Taiwan		Application
57	11/828,810	United States of America	QUALCOMM Incorporated	Application
	097128526	Taiwan		Application
	PCT/US2008/070863	Patent Cooperation Treaty		Application
58	11/734,656	United States of America	QUALCOMM Incorporated	Application
	200780041244.2	China		Application
	07863730.3	European Patent		Application
	2399/DELNP/2009	India		Application
	2009-536393	Japan		Application
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	PI0717956-1	Brazil		Application
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	200780039523.5	China		Application
	09110917.0	Hong Kong		Application
	07863984.6	European Patent		Application
	W-00200901201	Indonesia		Application
	197660	Israel		Application
	684/MUMNP/2009	India		Application
	2009-536445	Japan		Application
	10-2009-7011830	Korea Republic of (KR)		Application
	MX/a/2009/004835	Mexico		Application
	PI20091108	Malaysia		Application
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	200901870-6	Singapore		Application
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60	11/940,122	United States of America	QUALCOMM Incorporated	Application
	2007319261	Australia		Application
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	200780041845.3	China		Application
	09111063.0	Hong Kong		Application
	07864424.2	European Patent		Application
	09075354.2	European Patent		Application
	W-00200901622	Indonesia		Application
	198419	Israel		Application
	894/MUMNP/2009	India		Application
	2009-537335	Japan		Application
	2009-7012166	Korea Republic of (KR)		Application

	MX/a/2009/005086	Mexico		Application
	PI 20091808	Malaysia		Application
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	1-2009-500817	Philippines		Application
	2009122491	Russian Federation		Application
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61	12/351,535	United States of America	QUALCOMM Incorporated	Application
	98107738	Taiwan		Application
	PCT/US2009/036691	Patent Cooperation Treaty		Application
62	12/060,789	United States of America	QUALCOMM Incorporated	Application
	2008237266	Australia		Application
	PI0809481-0	Brazil		Application
	2679891	Canada		Application
	200880009842.6	China		Application
	10102982.4	Hong Kong		Application
	08733115.3	European Patent		Application
	W-00200902786	Indonesia		Application
	200595	Israel		Application
	1636/MUMNP/2009	India		Application
	2010-502303	Japan		Application
	10-2009-7022970	Korea Republic of (KR)		Application
	MX/a/2009/010356	Mexico		Application
	PI 20093570	Malaysia		Application
	579278	New Zealand		Application
	1-2009-501642	Philippines		Application
	2009140395	Russian Federation		Application
	200905705-0	Singapore		Application
	097112431	Taiwan		Application
	200911130	Ukraine		Application
	1-2009-02195	Vietnam		Application
63	12/051,209	United States of America	QUALCOMM Incorporated	Application
	2008228728	Australia		Application
	PI0808971-0	Brazil		Application
	2679337	Canada		Application

	200880008814.2	China		Application
	10102799.7	Hong Kong		Application
	08732711.0	European Patent		Application
	W-00200902564	Indonesia		Application
	200558	Israel		Application
	1596/MUMNP/2009	India		Application
	2010-501137	Japan		Application
	10-2009-7021960	Korea Republic of (KR)		Application
	MX/a/2009/010095	Mexico		Application
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64	12/051,758	United States of America	QUALCOMM Incorporated	Application
	200880008722.4	China		Application
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	1611/MUMNP/2009	India		Application
	2010-501139	Japan		Application
	10-2009-7021878	Korea Republic of (KR)		Application
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65	12/051,218	United States of America	QUALCOMM Incorporated	Application
	2008228734	Australia		Application
	PI0809199-4	Brazil		Application
	2679362	Canada		Application
	200880008802.X	China		Application
	10102983.3	Hong Kong		Application
	08732718.5	European Patent		Application
	W-00200902933	Indonesia		Application
	200556	Israel		Application
	1595/MUMNP/2009	India		Application
	2010-501140	Japan		Application
	10-2009-7021864	Korea Republic of (KR)		Application

	MX/a/2009/010100	Mexico		Application
	PI 20093550	Malaysia		Application
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	WO08116199	Philippines		Application
	2009138742	Russian Federation		Application
	200905632-6	Singapore		Application
	097110224	Taiwan		Application
	200910621	Ukraine		Application
	1-2009-02237	Vietnam		Application
66	12/104,840	United States of America	QUALCOMM Incorporated	Application
	200880012410.0	China		Application
	08746216.4	European Patent		Application
	1834/MUMNP/2009	India		Application
	2010-504264	Japan		Application
	10-2009-7024025	Korea Republic of (KR)		Application
67	12/014,929	United States of America	QUALCOMM Incorporated	Application
	PCT/US2009/030903	Patent Cooperation Treaty		Application
68	12/176,376	United States of America	QUALCOMM Incorporated	Application
	PENDING	Australia		Application
	PENDING	Brazil		Application
	2692822	Canada		Application
	PENDING	China		Application
	08796350.0	European Patent		Application
	W-00201000533	Indonesia		Application
	203192	Israel		Application
	54/MUMNP/2010	India		Application
	PENDING	Japan		Application
	10-2010-7003847	Korea Republic of (KR)		Application
	MX/a/2010/000794	Mexico		Application
	PI 2010000090	Malaysia		Application
	582503	New Zealand		Application
	1-2010-500081	Philippines		Application
	2010106123	Russian Federation		Application
	201000175-8	Singapore		Application
	1-2010-00412	Vietnam		Application
69	12/122,897	United States of America	QUALCOMM Incorporated	Application

	PCT/US2009/043572	Patent Cooperation Treaty		Application
70	12/357,976	United States of America	QUALCOMM Incorporated	Application
	PCT/US2009/031770	Patent Cooperation Treaty		Application
71	12/260,250	United States of America	QUALCOMM Incorporated	Application
	PENDING	Canada		Application
	PENDING	China		Application
	08844813.9	European Patent		Application
	2027/CHENP/2010	India		Application
	PENDING	Japan		Application
	PENDING	Singapore		Application
	097141866	Taiwan		Application
	PCT/US2008/081873	Patent Cooperation Treaty		Application
72	12/355,657	United States of America	QUALCOMM Incorporated	Application
73	12/370,478	United States of America	QUALCOMM Incorporated	Application
	PCT/US2009/034010	Patent Cooperation Treaty		Application
74	12/419,193	United States of America	QUALCOMM Incorporated	Application
	PCT/US2009/039800	Patent Cooperation Treaty		Application
75	12/419,184	United States of America	QUALCOMM Incorporated	Application
	PCT/US2009/039803	Patent Cooperation Treaty		Application
76	6,307,487	United States of America	QUALCOMM Incorporated	Granted
	767140	Australia		Granted
	6,373,406	United States of America		Granted
	6,614,366	United States of America		Granted
	7,057,534	United States of America		Granted
	7,233,264	United States of America		Granted
	11/738,866	United States of America		Application
	11/841,954	United States of America		Allowed
	2345237	Canada		Granted
	EP1116335	Germany (Federal Republic of)		Granted
	EP1241795	Germany (Federal Republic of)		Granted
	EP1116335	European Patent		Granted
	EP1241795	European Patent		Granted
	09007850.2	European Patent		Application
	EP1116335	France		Granted
	EP1241795	France		Granted
	EP1116335	United Kingdom		Granted

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	1038995	Hong Kong		Granted
	140705	Israel		Granted
	EP1116335	Italy		Granted
	EP1241795	Italy		Granted
	3976163	Japan		Granted
	3809957	Japan		Granted
	598662	Korea Republic of (KR)		Granted
	79667	Singapore		Granted
77	7,072,971	United States of America	QUALCOMM Incorporated	Granted
	7,512,697	United States of America		Granted
	12/370,193	United States of America		Application
78	11/679,170	United States of America	QUALCOMM Incorporated	Application
	NI-194502	Taiwan		Granted
79	6,073,250	United States of America	QUALCOMM Incorporated	Granted
80	6,081,909	United States of America	QUALCOMM Incorporated	Granted
81	6,163,870	United States of America	QUALCOMM Incorporated	Granted
82	7,068,729	United States of America	QUALCOMM Incorporated	Granted
	7,720,174	United States of America		Granted
	7,711,068	United States of America		Granted
	02828117.9	China		Application
	02794439.6	European Patent		Application
	1566/CHENP/2004	India		Application
	4157041	Japan		Granted
	924295	Korea Republic of (KR)		Granted
	I280748	Taiwan		Granted
83	7,293,222	United States of America	QUALCOMM Incorporated	Granted
84	6,856,263	United States of America	QUALCOMM Incorporated	Granted
	7,030,785	United States of America		Granted
	7,265,688	United States of America		Granted
	7,633,413	United States of America		Granted
	ZL03813796.8	China		Granted
	03757482.9	European Patent		Application
	HK1082127	Hong Kong		Granted
	3079/CHENP/2004	India		Application
	4224022	Japan		Granted

	950186	Korea Republic of (KR)		Granted
85	6,909,383	United States of America	QUALCOMM Incorporated	Granted
	7,394,407	United States of America		Granted
	7,532,132	United States of America		Granted
	12/418,378	United States of America		Application
	ZL200380104307.6	China		Granted
	03808111.3	European Patent		Application
	06100646.2	Hong Kong		Application
	220074	India		Granted
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	10-2005-7005861	Korea Republic of (KR)		Application
86	7,418,651	United States of America	QUALCOMM Incorporated	Granted
	12/197,993	United States of America		Application
	200580001026.7	China		Application
	05747947.9	European Patent		Application
	10002379.5	European Patent		Application
	07105599.7	Hong Kong		Application
	2427/CHENP/2006	India		Application
	2007-511719	Japan		Application
	10-2006-7009106	Korea Republic of (KR)		Application
87	7,721,184	United States of America	QUALCOMM Incorporated	Granted
	12/331,268	United States of America		Application
88	12/768,506	United States of America	QUALCOMM Incorporated	Application
	61/179,634	United States of America		Application
89	12/549,560	United States of America	QUALCOMM Incorporated	Application
	61/235,285	United States of America		Application
	61/257,146	United States of America		Application
90	61/249,507	United States of America	QUALCOMM Incorporated	Application
	61/249,564	United States of America		Application
91	6,760,772	United States of America	QUALCOMM Incorporated	Granted
	10/826,579	United States of America		Allowed
92	10/236,657	United States of America	QUALCOMM Incorporated	Allowed
	2002324904	Australia		Application
	PI0212361-4	Brazil		Application
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	02821314.9	China		Application

	200710152767.6	China		Application
	05102988.5	Hong Kong		Application
	08110124.0	Hong Kong		Application
	234124	India		Granted
	PA/a/2004/002212	Mexico		Application
	1-2004-500451	Philippines		Granted
	2004110228	Russian Federation		Application
	103555	Singapore		Granted
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93	10/922,423	United States of America	QUALCOMM Incorporated	Allowed
	PI0413697-7	Brazil		Application
	2535899	Canada		Application
	200480028696.3	China		Application
	04781829.9	European Patent		Application
	07103996.1	Hong Kong		Application
	602/CHENP/2006	India		Application
	3357/CHENP/2009	India		Application
	2006-524096	Japan		Application
	2006-7003595	Korea Republic of (KR)		Application
	271298	Mexico		Granted
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94	10/922,405	United States of America	QUALCOMM Incorporated	Application
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	2535904	Canada		Application
	200480028692.5	China		Application
	04781830.7	European Patent		Application
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	600/CHENP/2006	India		Application
	2006-524097	Japan		Application
	2006-7003596	Korea Republic of (KR)		Application
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	093125259	Taiwan		Application
95	12/180,305	United States of America	QUALCOMM Incorporated	Application
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	097128651	Taiwan		Application

96	11/933,264	United States of America	QUALCOMM Incorporated	Application
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	08845106.7	European Patent		Application
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	135/MUMNP/2010	India		Application
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97	097142226	Taiwan	QUALCOMM Incorporated	Application
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Disclosure Statement and Licensing Declaration

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Email: trouse@qualcomm.com

URL (optional): www.qualcomm.com

Identification of ATSC Specification Document relevant to the Disclosure Statement:

Number: ATSC Specification, ATSC NRT

Title: ATSC Non-Real-Time Content Delivery

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Completed By:

Name of Participant: QUALCOMM Incorporated

Name of Representative: Thomas R. Rouse

Title of Representative: VP, QTL Patent Counsel

Signature: 

Place, Date: San Diego, CA May 13, 2010